CMLDM7002A
CMLDM7002AG*
CMLDM7002AJ

SURFACE MOUNT SILICON DUAL N-CHANNEL ENHANCEMENT-MODE MOSFETS



SOT-563 CASE

* Device is ***Halogen Free*** by design

Central Semiconductor Corp.

www.centralsemi.com

DESCRIPTION:

These CENTRAL SEMICONDUCTOR devices are dual N-Channel enhancement-mode MOSFETs, manufactured by the N-Channel DMOS Process, designed for high speed pulsed amplifier and driver applications. The CMLDM7002A utilizes the USA pinout configuration, while the CMLDM7002AJ utilizes the Japanese pinout configuration. These devices offer low $r_{DS\ (ON)}$ and low $V_{DS(ON)}$.

MARKING CODES: CMLDM7002A: L02
CMLDM7002AG*: C2G
CMLDM7002AJ: 02J

MAXIMUM RATINGS: (T_A=25°C)	**SYMBOL**		**UNITS**
Drain-Source Voltage	V_{DS}	60	V
Drain-Gate Voltage	V_{DG}	60	V
Gate-Source Voltage	V_{GS}	40	V
Continuous Drain Current	I_D	280	mA
Continuous Source Current (Body Diode)	I_S	280	mA
Maximum Pulsed Drain Current	I_{DM}	1.5	A
Maximum Pulsed Source Current	I_{SM}	1.5	A
Power Dissipation (Note 1)	P_D	350	mW
Power Dissipation (Note 2)	P_D	300	mW
Power Dissipation (Note 3)	P_D	150	mW
Operating and Storage Junction Temperature	T_J, T_{stg}	-65 to +150	°C
Thermal Resistance	Θ_{JA}	357	°C/W

ELECTRICAL CHARACTERISTICS PER TRANSISTOR: (T_A=25°C unless otherwise noted)

SYMBOL	**TEST CONDITIONS**	**MIN**	**MAX**	**UNITS**
I_{GSSF}, I_{GSSR}	V_{GS}=20V, V_{DS}=0		100	nA
I_{DSS}	V_{DS}=60V, V_{GS}=0		1.0	μA
I_{DSS}	V_{DS}=60V, V_{GS}=0, T_J=125°C		500	μA
$I_{D(ON)}$	V_{GS}=10V, V_{DS}=10V	500		mA
BV_{DSS}	V_{GS}=0, I_D=10μA	60		V
$V_{GS(th)}$	V_{DS}=V_{GS}, I_D=250μA	1.0	2.5	V
$V_{DS(ON)}$	V_{GS}=10V, I_D=500mA		1.0	V
$V_{DS(ON)}$	V_{GS}=5.0V, I_D=50mA		0.15	V
V_{SD}	V_{GS}=0, I_S=400mA		1.2	V
$r_{DS(ON)}$	V_{GS}=10V, I_D=500mA		2.0	Ω
$r_{DS(ON)}$	V_{GS}=10V, I_D=500mA, T_J=125°C		3.5	Ω
$r_{DS(ON)}$	V_{GS}=5.0V, I_D=50mA		3.0	Ω
$r_{DS(ON)}$	V_{GS}=5.0V, I_D=50mA, T_J=125°C		5.0	Ω
g_{FS}	V_{DS}=10V, I_D=200mA	80		mS

Notes: (1) Ceramic or aluminum core PC Board with copper mounting pad area of 4.0mm^2
(2) FR-4 Epoxy PC Board with copper mounting pad area of 4.0mm^2
(3) FR-4 Epoxy PC Board with copper mounting pad area of 1.4mm^2

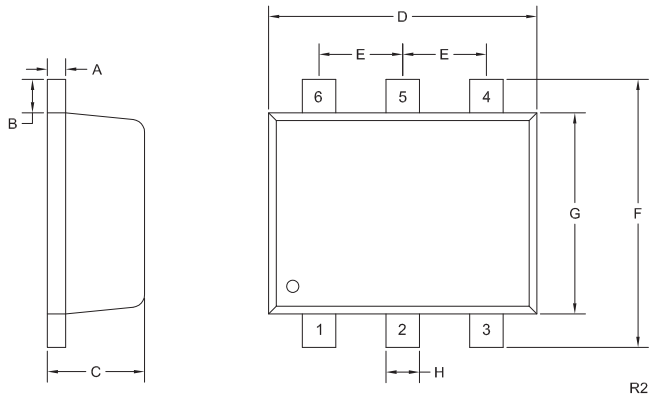
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ELECTRICAL CHARACTERISTICS PER TRANSISTOR - Continued: (T_A=25°C unless otherwise noted)

SYMBOL	TEST CONDITIONS	TYP	MAX	UNITS
C_{rss}	V_{DS}=25V, V_{GS}=0, f=1.0MHz		5.0	pF
C_{iss}	V_{DS}=25V, V_{GS}=0, f=1.0MHz		50	pF
C_{oss}	V_{DS}=25V, V_{GS}=0, f=1.0MHz		25	pF
$Q_{g(tot)}$	V_{DS}=30V, V_{GS}=4.5V, I_D=100mA	0.592		nC
Q_{gs}	V_{DS}=30V, V_{GS}=4.5V, I_D=100mA	0.196		nC
Q_{gd}	V_{DS}=30V, V_{GS}=4.5V, I_D=100mA	0.148		nC
t_{on}, t_{off}	V_{DD}=30V, V_{GS}=10V, I_D=200mA			
	R_G=25Ω, R_L=150Ω		20	ns

SOT-563 CASE - MECHANICAL OUTLINE

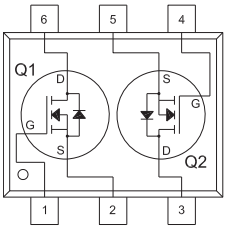


DIMENSIONS				
	INCHES		MILLIMETERS	
SYMBOL	MIN	MAX	MIN	MAX
A	0.0027	0.007	0.07	0.18
B	0.008		0.20	
C	0.017	0.024	0.45	0.60
D	0.059	0.067	1.50	1.70
E	0.020		0.50	
F	0.059	0.067	1.50	1.70
G	0.043	0.051	1.10	1.30
H	0.006	0.012	0.15	0.30

SOT-563 (REV: R2)

PIN CONFIGURATIONS

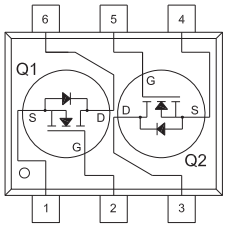
CMLDM7002A (USA Pinout)
CMLDM7002AG*



LEAD CODE:
1) Gate Q1
2) Source Q1
3) Drain Q2
4) Gate Q2
5) Source Q2
6) Drain Q1

MARKING CODES:
CMLDM7002A: L02
CMLDM7002AG*: C2G

CMLDM7002AJ (Japanese Pinout)



LEAD CODE:
1) Source Q1
2) Gate Q1
3) Drain Q2
4) Source Q2
5) Gate Q2
6) Drain Q1

MARKING CODE: 02J

* Device is ***Halogen Free*** by design

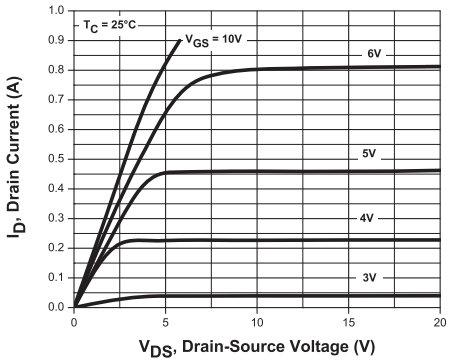
R8 (8-June 2015)

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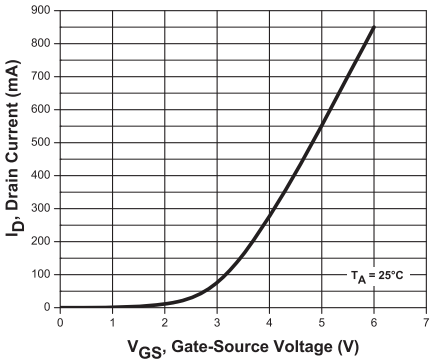
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TYPICAL ELECTRICAL CHARACTERISTICS

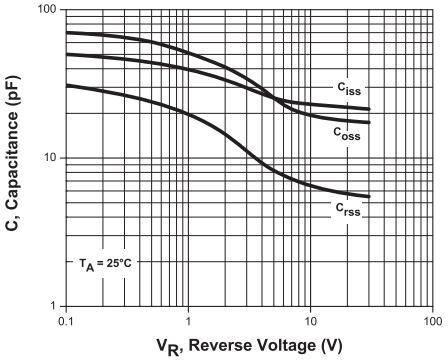
Output Characteristics



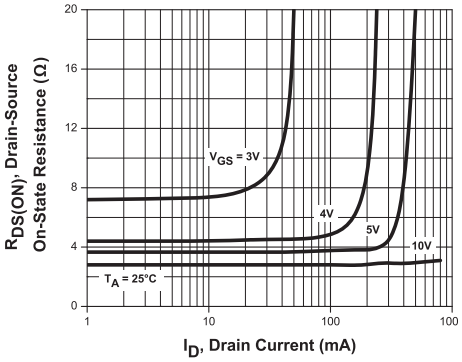
Transfer Characteristics



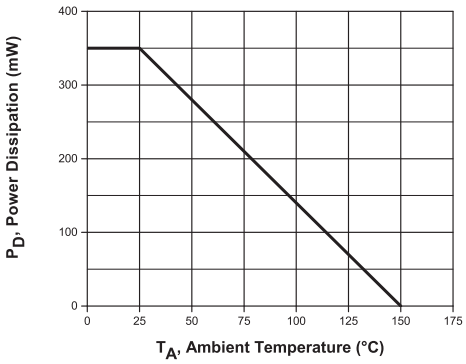
Capacitance



Drain Source On Resistance



Power Derating



R8 (8-June 2015)

OUTSTANDING SUPPORT AND SUPERIOR SERVICES

PRODUCT SUPPORT

Central's operations team provides the highest level of support to insure product is delivered on-time.

- Supply management (Customer portals)
- Inventory bonding
- Consolidated shipping options
- Custom bar coding for shipments
- Custom product packing

DESIGNER SUPPORT/SERVICES

Central's applications engineering team is ready to discuss your design challenges. Just ask.

- Free quick ship samples (2nd day air)
- Online technical data and parametric search
- SPICE models
- Custom electrical curves
- Environmental regulation compliance
- Customer specific screening
- Up-screening capabilities
- Special wafer diffusions
- PbSn plating options
- Package details
- Application notes
- Application and design sample kits
- Custom product and package development

REQUESTING PRODUCT PLATING

1. If requesting Tin/Lead plated devices, add the suffix " TIN/LEAD" to the part number when ordering (example: 2N2222A TIN/LEAD).
2. If requesting Lead (Pb) Free plated devices, add the suffix " PBFREE" to the part number when ordering (example: 2N2222A PBFREE).

CONTACT US

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